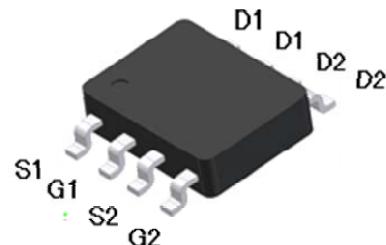
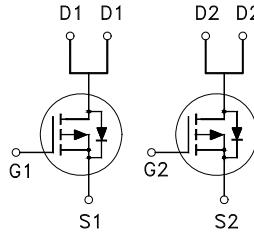


P-Channel Logic Level Enhancement Mode Field Effect Transistor
Product Summary:

BV_{DSS}	-20V
$R_{DS(on)}$ (MAX.)	20mΩ
I_D	-8.5A



Pb-Free Lead Plating & Halogen Free


ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNIT
Gate-Source Voltage		V_{GS}	± 12	V
Continuous Drain Current	$T_A = 25^\circ\text{C}$	I_D	-8.5	A
	$T_A = 70^\circ\text{C}$		-6	
Pulsed Drain Current ¹		I_{DM}	-34	
Power Dissipation	$T_A = 25^\circ\text{C}$	P_D	2	W
	$T_A = 70^\circ\text{C}$		1.28	
Operating Junction & Storage Temperature Range		T_j, T_{stg}	-55 to 150	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNIT
Junction-to-Case	$R_{\theta JC}$		25	°C / W
Junction-to-Ambient ³	$R_{\theta JA}$		62.5	

¹Pulse width limited by maximum junction temperature.

²Duty cycle ≤ 1%

³62.5°C / W when mounted on a 1 in² pad of 2 oz copper.

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$, Unless Otherwise Noted)

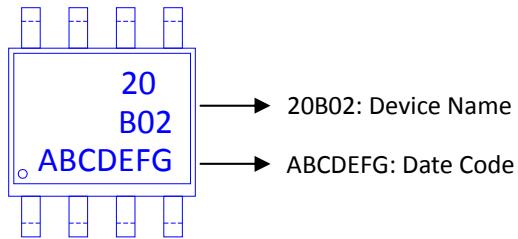
PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{GS} = 0V, I_D = -250\mu\text{A}$	-20			V
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = -250\mu\text{A}$	-0.4	-0.75	-1.2	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0V, V_{GS} = \pm 12V$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -16V, V_{GS} = 0V$			-1	μA
		$V_{DS} = -12V, V_{GS} = 0V, T_J = 125^\circ\text{C}$			-10	
On-State Drain Current ¹	$I_{D(\text{ON})}$	$V_{DS} = -5V, V_{GS} = -4.5V$	-8.5			A
Drain-Source On-State Resistance ¹	$R_{DS(\text{ON})}$	$V_{GS} = -4.5V, I_D = -8.5A$		15	20	$\text{m}\Omega$
		$V_{GS} = -2.5V, I_D = -4.5A$		19	25	
		$V_{GS} = -1.8V, I_D = -2.5A$		26	40	
Forward Transconductance ¹	g_{fs}	$V_{DS} = -5V, I_D = -8.5A$		22		S
DYNAMIC						
Input Capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = -10V, f = 1\text{MHz}$		3050		pF
Output Capacitance	C_{oss}			460		
Reverse Transfer Capacitance	C_{rss}			410		
Total Gate Charge ^{1,2}	$Q_g(V_{GS}=-4.5V)$	$V_{DS} = -10V, V_{GS} = -4.5V, I_D = -8.5A$		27		nC
	$Q_g(V_{GS}=-2.5V)$			16.5		
Gate-Source Charge ^{1,2}	Q_{gs}			2.2		
Gate-Drain Charge ^{1,2}	Q_{gd}			6.8		
Turn-On Delay Time ^{1,2}	$t_{d(on)}$	$V_{DS} = -10V, I_D = -1A, V_{GS} = -4.5V, R_{GS} = 6\Omega$		20		nS
Rise Time ^{1,2}	t_r			50		
Turn-Off Delay Time ^{1,2}	$t_{d(off)}$			90		
Fall Time ^{1,2}	t_f			60		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_c = 25^\circ\text{C}$)						
Continuous Current	I_S				-2.3	A
Pulsed Current ³	I_{SM}				-9.2	
Forward Voltage ¹	V_{SD}	$I_F = I_S, V_{GS} = 0V$			-1.2	V

¹Pulse test : Pulse Width $\leq 300 \mu\text{sec}$, Duty Cycle $\leq 2\%$.²Independent of operating temperature.³Pulse width limited by maximum junction temperature.

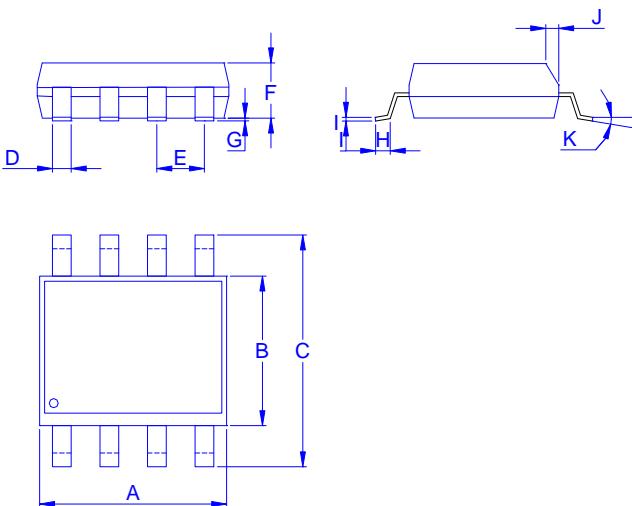
Ordering & Marking

Information:

Device Name: LB20B02HD for SOP-8



Outline Drawing



Dimension in mm

Dimension	A	B	C	D	E	F	G	H	I	J	K
Min.	4.70	3.70	5.80	0.33		1.20	0.08	0.40	0.19	0.25	0°
Typ.					1.27						
Max.	5.10	4.10	6.20	0.51		1.62	0.28	0.83	0.26	0.50	8°

TYPICAL CHARACTERISTICS

